

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

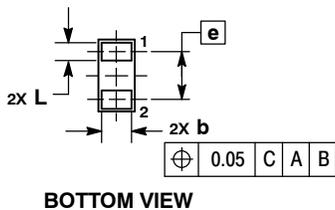
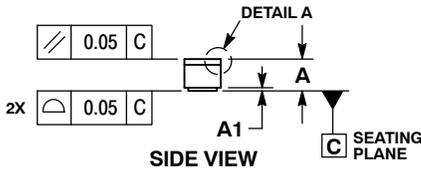
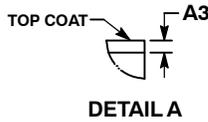
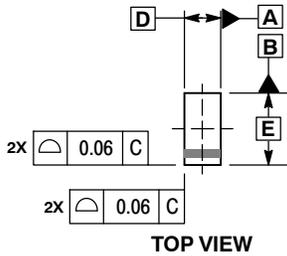
ON Semiconductor®



SCALE 8:1

DSN2, 0.6x0.3, 0.4P, (0201)
CASE 152AS
ISSUE A

DATE 23 JAN 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS		
DIM	MIN	MAX
A	0.24	0.30
A1	0.00	0.01
A3	0.04	REF
b	0.20	0.25
D	0.30	BSC
E	0.60	BSC
e	0.40	BSC
L	0.10	0.18

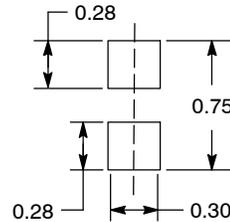
GENERIC MARKING DIAGRAM*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DSN2, 0.6X0.3, 0.4P, (0201)	PAGE 1 OF 2

